



Material Content Data Sheet



Sales Product Name	BDP 947 H6327			Issued		11. December 2019		
MA#	MA001201210							
Package	PG-SOT223-4-24			Weight*		107.31 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.011	0.01		103	
	noble metal	gold	7440-57-5	0.043	0.04		399	
	inorganic material	silicon	7440-21-3	0.522	0.49	0.54	4864	5366
leadframe	inorganic material	silicon	7440-21-3	0.009	0.01		79	
	non noble metal	titanium	7440-32-6	0.043	0.04		397	
	non noble metal	chromium	7440-47-3	0.128	0.12		1192	
	non noble metal	copper	7440-50-8	42.459	39.57	39.74	395661	397329
wire	non noble metal	copper	7440-50-8	0.123	0.11	0.11	1148	1148
encapsulation	organic material	carbon black	1333-86-4	0.620	0.58		5779	
	plastics	epoxy resin	-	9.302	8.67		86686	
	inorganic material	silicondioxide	60676-86-0	52.093	48.54	57.79	485440	577905
leadfinish	non noble metal	tin	7440-31-5	1.464	1.36	1.36	13642	13642
plating	noble metal	silver	7440-22-4	0.495	0.46	0.46	4610	4610
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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